

Docket No: 030712-22 Application No.: 10/766,938

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Seiji ANDOH

Serial No. 10/766,938

Filed: 01/30/2004

For: SEMICONDUCTOR DEVICE

) Group Art Unit: 2891

) Examiner: Douglas M. Menz

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CERTIFICATE OF MAILING OR TRANSMISSION [37 CFR 1.8(a)]

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Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Enclosed please find one (1) sheet of formal drawings (Fig. 3) for review by the Patent and Trademark Office. In substitute Fig. 3, a solder resist layer 34a existing in region excluding regions 148 indicated as a region defined by arrows P and Q are discontinuously deposited. Support for this amendment to Fig. 3 is based on the description at page 18, lines 11-13 and lines 21-22. Further, the amended figure corresponds to Fig. 3 of Japanese patent application JP 2003-372783 which is the Japanese priority application of the present application.

Respectfully submitted.

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